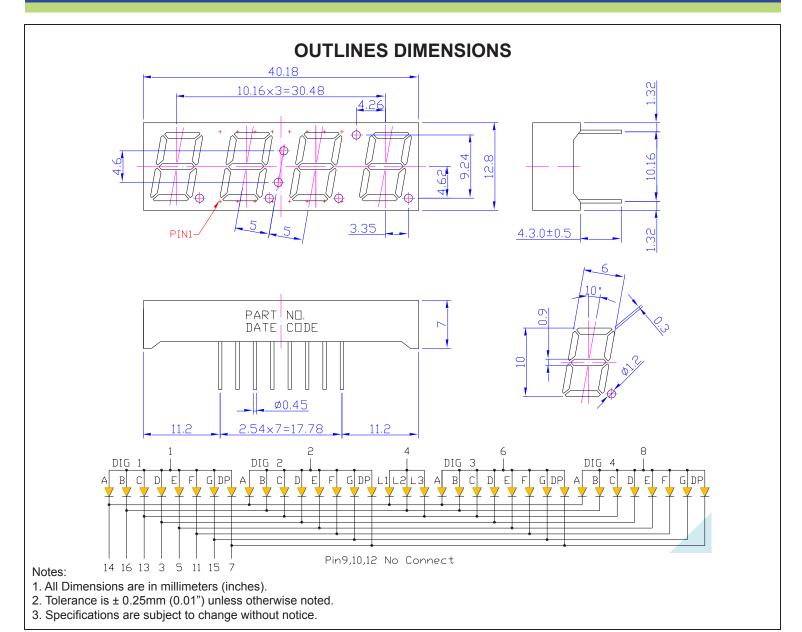
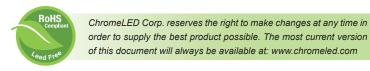


## SPECIFICATIONS CDQA39A2WF



Part Number	Chip Material	Color of Emission	Lens Type	Description
CDQA39A2WF	InGaAlP	Orange	White Segment	Common Anode





#### **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Power Dissipation	Po	70	mW	
Pulse Current Forward Current	lfP	90	mA	
Continuous Forward Current	lF	25	mA	
Reverse Voltage	VR	5	V	
Operating Temperature Range	Topr	-25~+85	°C	
Storage Temperature Range	Тѕтс	-25~+85	°C	

IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec

### **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

Doromotor	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	I <sub>F</sub> = 20mA	40	80	-	mcd
Forward Voltage	VF	I <sub>F</sub> = 20mA	1	2.05	2.4	V
Reverse Leakage Current	lR	V <sub>R</sub> = 5V	1	-	10	μΑ
Peak Wavelength	<b>λ</b> P	I⊧ = 20mA	1	610	1	nm
Dominant Wavelength	λD	I⊧ = 20mA	-	606	-	nm
Spectral Line half-width	Δλ	I⊧ = 20mA	-	20	-	nm



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



#### **OPTICAL CHARACTERISTIC CURVES**

# Typical Electro-optical Characteristic Curves (25 °C Free Air Temperature Unless Otherwise Specified)

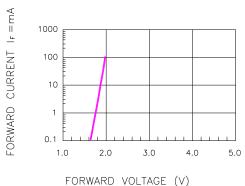
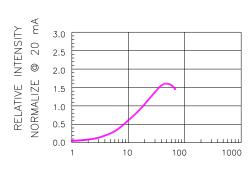


Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE



FORWARD CURRENT (mA)
Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

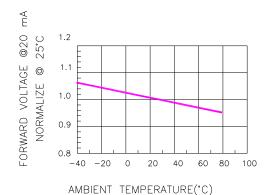


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

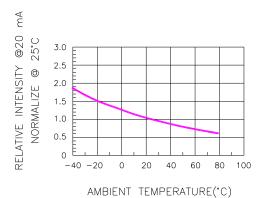


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

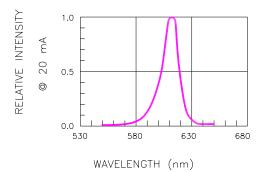
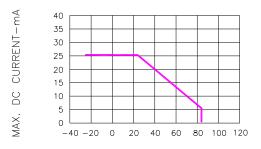


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH



AMBIENT TEMPERATURE (TA)-°C

Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



#### **SOLDERING CONDITIONS – LAMP TYPE LED**

- \* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- \* Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering				
Temperature Soldering Time Position	3mm Series	Others		
	300 °C Max	350 °C Max		
	3 Second Max	3 Second Max		
	No closer than 3mm from the	No closer than 3mm from the		
	base of the epoxy	base of the epoxy		

- \* Do not apply any stress to the lead. Particularly when heated.
- \* The LED must not be repositioned after soldering.
- \* After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- \* Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- \* When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- \* Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

